

# 2N7051

# **NPN Darlington Transistor**

- This device designed for applications requiring extremely high gain at collector currents to 1.0A and high breakdown voltage.
- Sourced from Process 06.
- See 2N7052 for Characteristics.



### 1. Emitter 2. Collector 3. Base

# **NPN Epitaxial Silicon Transistor**

## Absolute Maximum Ratings\* T<sub>A</sub>=25°C unless otherwise noted

Symbol	Parameter	Ratings	Units
V <sub>CEO</sub>	Collector-Emitter Voltage	100	V
$V_{CBO}$	Collector-Base Voltage	100	V
V <sub>EBO</sub>	Emitter-Base Voltage	12	V
I <sub>C</sub>	Collector Current	1.5	А
T <sub>J</sub> , T <sub>STG</sub>	Storage Temperature	-55 ~ 150	°C

<sup>\*</sup> These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

- These rtings are based on a maximum junction temperature of 150 degrees C.
   These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

### Electrical Characteristics T<sub>A</sub>=25°C unless otherwise noted

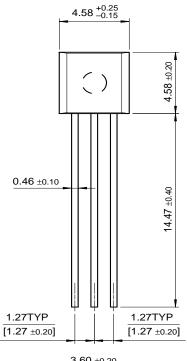
Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
Off Charac	Off Characteristics					
BV <sub>CEO</sub>	Collector-Emitter Breakdown Voltage *	$I_C = 1.0 \text{mA}, I_B = 0$	100			V
BV <sub>CBO</sub>	Collector-Base Breakdown Voltage	$I_C = 100 \mu A, I_B = 0$	100			V
BV <sub>EBO</sub>	Emitter-Base Breakdown Voltage	$I_E = 1.0 \text{mA}, I_C = 0$	12			V
I <sub>CBO</sub>	Collector Cut-off Current	$V_{CB} = 80V, I_{E} = 0$			0.1	μΑ
I <sub>CES</sub>		$V_{CE} = 80V, I_{E} = 0$			0.2	μΑ
I <sub>EBO</sub>	Emitter Cut-off Current	$V_{EB} = 7.0V, I_C = 0$			0.1	μΑ
On Characteristics *						
h <sub>FE</sub>	DC Current Gain	$V_{CE} = 5.0V, I_{C} = 100mA$	10,000			
		$V_{CE} = 5.0V, I_{C} = 1.0A$	1,000		20,000	
V <sub>CE</sub> (sat)	Collector-Emitter Saturation Voltage	$I_C = 100 \text{mA}, I_B = 0.1 \text{mA}$			1.5	V
V <sub>BE</sub> (sat)	Base-Emitter Saturation Voltage	$I_C = 100 \text{mA}, V_{BE} = 5.0 \text{V}$			2.0	V
Small Signal Characteristics						
f <sub>T</sub>	Transition Frequency	$I_C = 100 \text{mA}, V_{CE} = 5.0 \text{V}$	200			MHz
h <sub>fe</sub>	Small Signal Current Gain	$V_{CE}$ =5.0V, $I_{C}$ = 100mA, f = 20MHz	10		100	

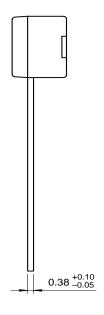
<sup>\*</sup> Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 1.0%

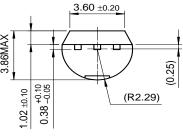
Thermal Characteristics T <sub>A</sub> =25°C unless otherwise noted				
Symbol	Parameter	Max.	Units	
$P_{D}$	Total Device Dissipation Derate above 25°C	625 5.0	mW mW/°C	
$R_{\theta JC}$	Thermal Resistance, Junction to Case 83.3 °C/\		°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	200	°C/W	

# **Package Dimensions**

TO-92







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